

SUGGESTED PCB LAYOUT  
(COMPONENT SIDE)

1.MATERIAL:

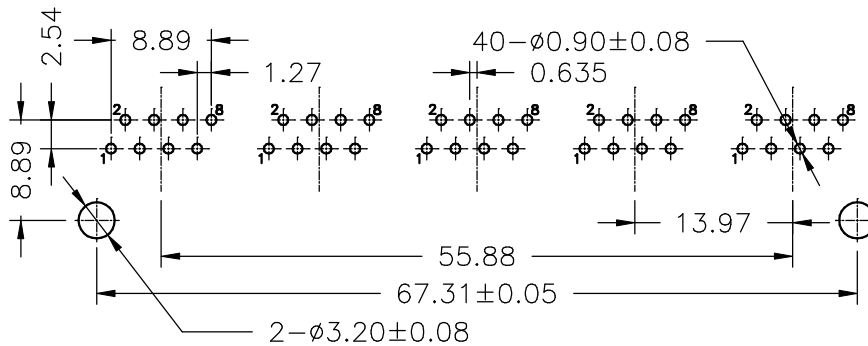
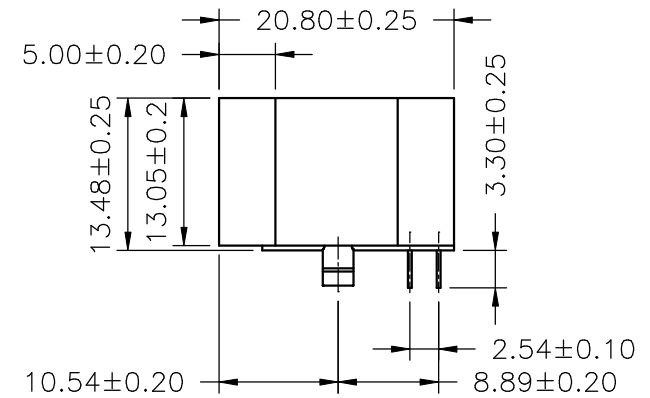
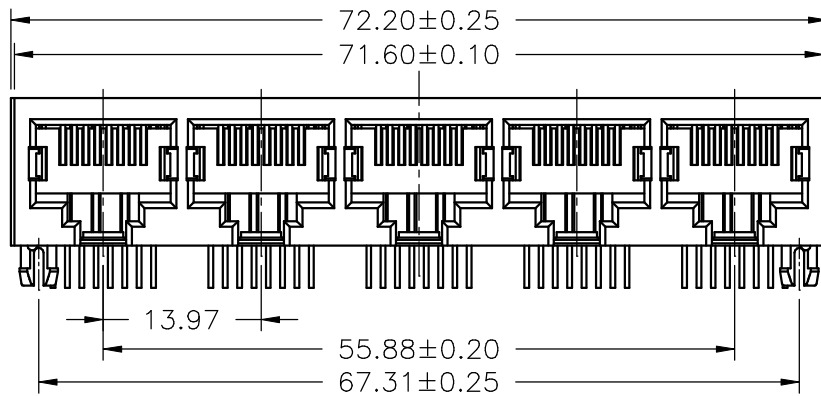
HOUSING: PBT, BLACK, UL94V-0  
 CONTACTS: 0.35[0.014] THICK PHOSPHOR BRONZE PLATED WITH  
 100μ" MINIMUM THICK TIN IN SOLDER AREA.  
 15μ" MINIMUM GOLD IN LOCALIZED PLATE AREA.  
 ENTIRE CONTACTS PLATED WITH 30μ" MINIMUM THICK NICKEL.

2.JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.

3.PART NUMBER: HRJ800615-U1588-F1

				JOINT TECH ELECTRONIC IND. CO., LTD. JOY DAY INDUSTRIAL CO., LTD.	
		UNIT	SCALE	SHEET	TITLE:
		mm[inch]		1 of 1	
		DRAWN BY	APPROVED BY		
		董正一	董正一		
		2004.08.23	2004.08.23		
		GENERAL TOLERANCE			
B1	REVISE	2005.12.30	X. X±0.25	ANGLE±	
B0	NEW RELEASE	2005.12.22	X. XX±0.15		
REV.	DESCRIPTION	DATE	X. XXX±0.05		
					DRAW NO. : HRJ800615-U1588-F1
					REV. B1

RJ45, MODULAR JACK,  
1X5, W/O LED, 8P, 8C,  
UNSHIELDED, THRU-HOLE





SUGGESTED PCB LAYOUT  
(COMPONENT SIDE)

1.MATERIAL:

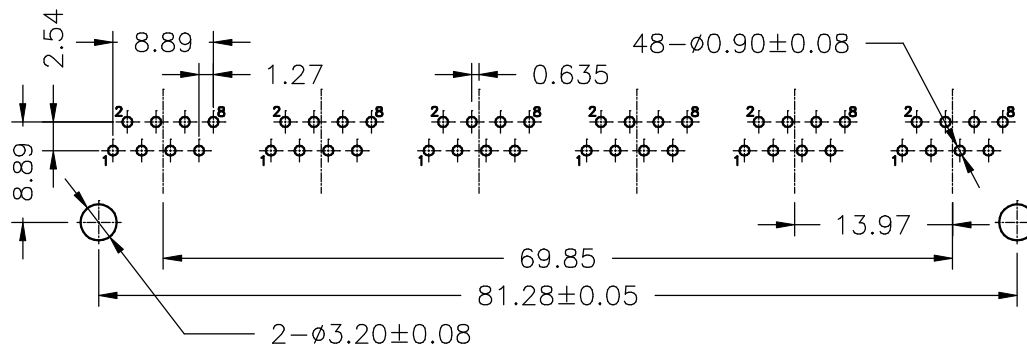
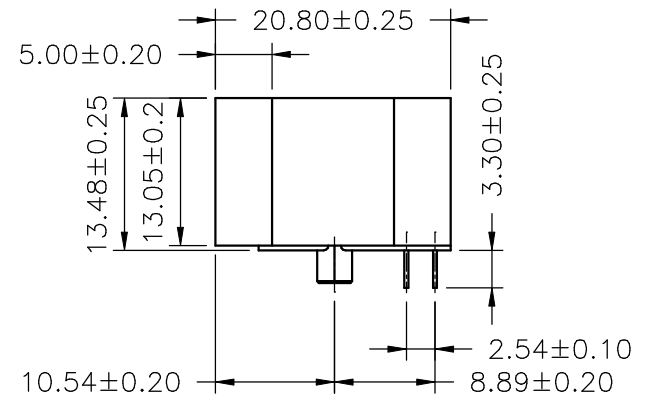
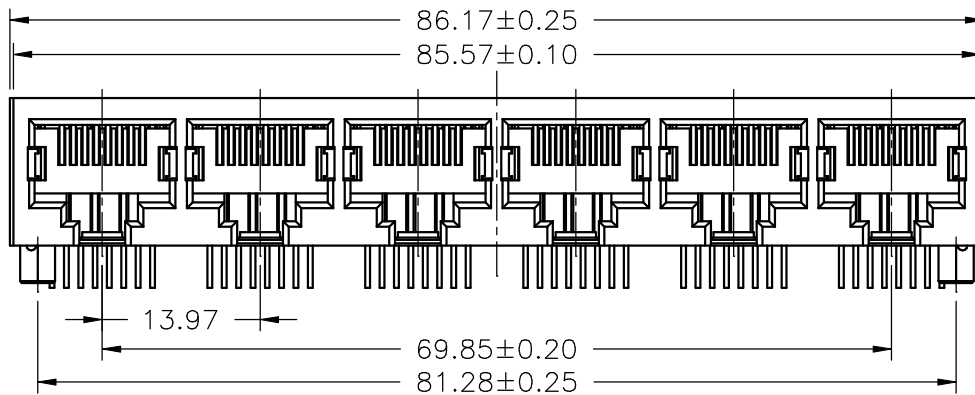
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2.JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.

3.PART NUMBER: HRJ800615-U1588-F2

				JOINT TECH ELECTRONIC IND. CO., LTD. JOY DAY INDUSTRIAL CO., LTD.	
		UNIT	SCALE	SHEET	TITLE:
		mm[inch]		1 of 1	
		DRAWN BY	APPROVED BY		
		董正一	董正一		
		2004.08.23	2004.08.23		
GENERAL TOLERANCE					
B1	REVISE	2005.12.30	X. X±0.25	ANGLE±	
B0	NEW RELEASE	2005.12.22	X. XX±0.15		
REV.	DESCRIPTION	DATE	X. XXX±0.05		
					DRAW NO. : HRJ800615-U1588-F2
					REV. B1

RJ45, MODULAR JACK,  
1X5, W/O LED, 8P, 8C,  
UNSHIELDED, THRU-HOLE



SUGGESTED PCB LAYOUT  
(COMPONENT SIDE)

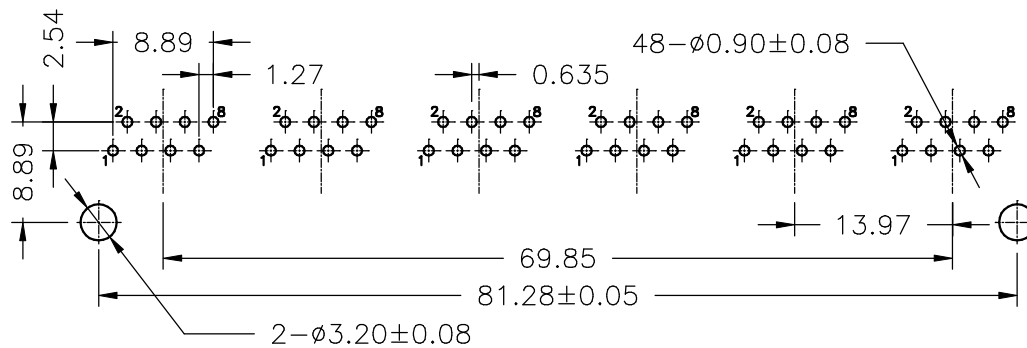
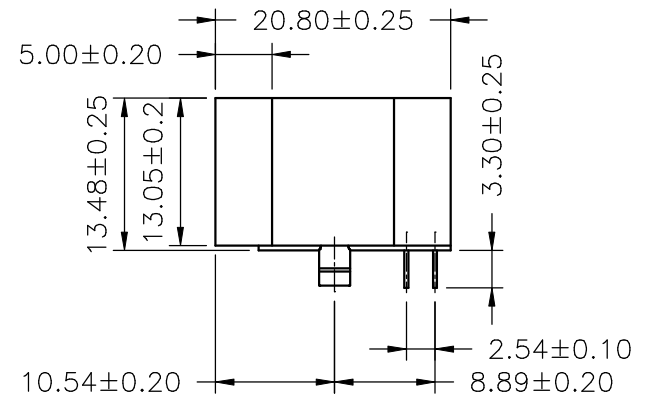
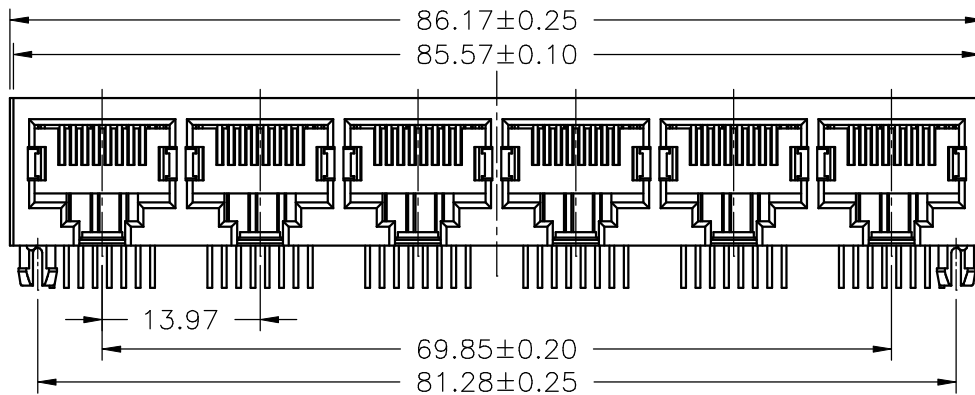
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2.JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.

3.PART NUMBER: HRJ800615-U1688-F1

		UNIT	SCALE	SHEET	TITLE:
		mm[inch]		1 of 1	RJ45, MODULAR JACK, 1X6, W/O LED, 8P, 8C, UNSHIELDED, THRU-HOLE
		DRAWN BY 董正一		APPROVED BY 董正一	
		2004.08.23		2004.08.23	
GENERAL TOLERANCE					
B1	REVISE	2005.12.30	X.X±0.25	ANGLE±	
B0	NEW RELEASE	2005.12.22	X.XX±0.15		
REV.	DESCRIPTION	DATE	X.XXX±0.05		
				DRAW NO. :	REV.
				HRJ800615-U1688-F1	B1



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2.JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.

3.PART NUMBER: HRJ800615-U1688-F2

						UNIT SCALE SHEET mm[inch] 1 of 1		TITLE: <b>RJ45, MODULAR JACK,          1X6, W/O LED, 8P, 8C,          UNSHIELDED, THRU-HOLE</b>	
						DRAWN BY 董正一 2004.08.23		APPROVED BY 董正一 2004.08.23	
				GENERAL TOLERANCE		B1 REVISE 2005.12.30 X.X±0.25 ANGLE±			
				B0 NEW RELEASE 2005.12.22 X.XX±0.15				REV. B1	
				REV. DESCRIPTION DATE X.XXX±0.05					